



A Boundary Scan Test Vehicle for Direct Chip Attach (DCA) Testing

Heather Parsons

Saverio D'Agostino

Genji Arakaki

Jet Propulsion Laboratory

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Topics

- *Background: Direct Chip Attach*
- *Test Methods*
- *What is boundary scan and how does it work*
- *How is it currently being used*
- *Usefulness to others*

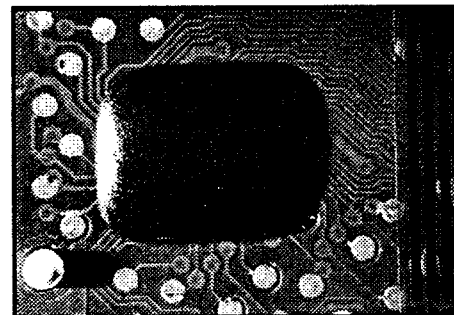


Background: What is Direct Chip Attach?

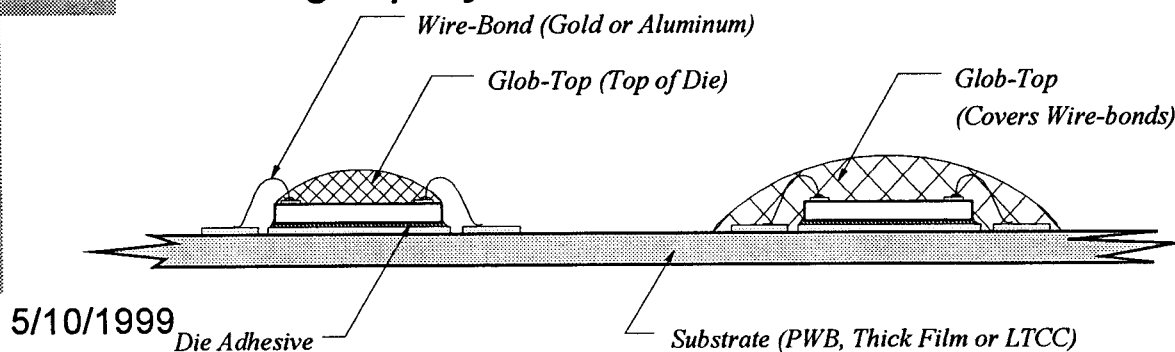
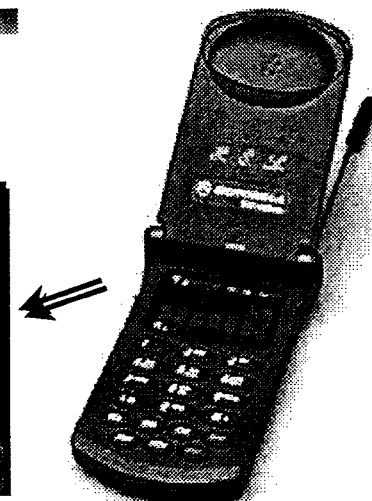
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- Equivalent to Chip-On-Board
- Bare die bonded directly to the printed wiring board
- Wire bonded
- Non-Hermetic Packaging
- To validate an encapsulation or passivation technology for New Millenium Deep Space - 2 (DS-2) and other flight projects

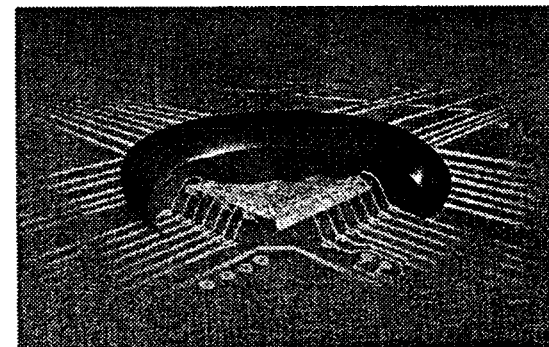
Motorola Star-Tac



Ref: Binghamton University web page (<http://www.ieec.binghamton.edu/ieec/>)



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Ref: Circuits Assembly, 1996

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Background: DCA Objectives

- *To design a substrate that*
 - *gives a realistic understanding of how the environment affects powered devices*
 - *provides information about the reliability of passivation technology*
- *Span wide range of part types*
- *Testing*
 - *Fast*
 - *Automated*
 - *Repetitive*
 - *Log data*

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Test Methods

Daisy Chain

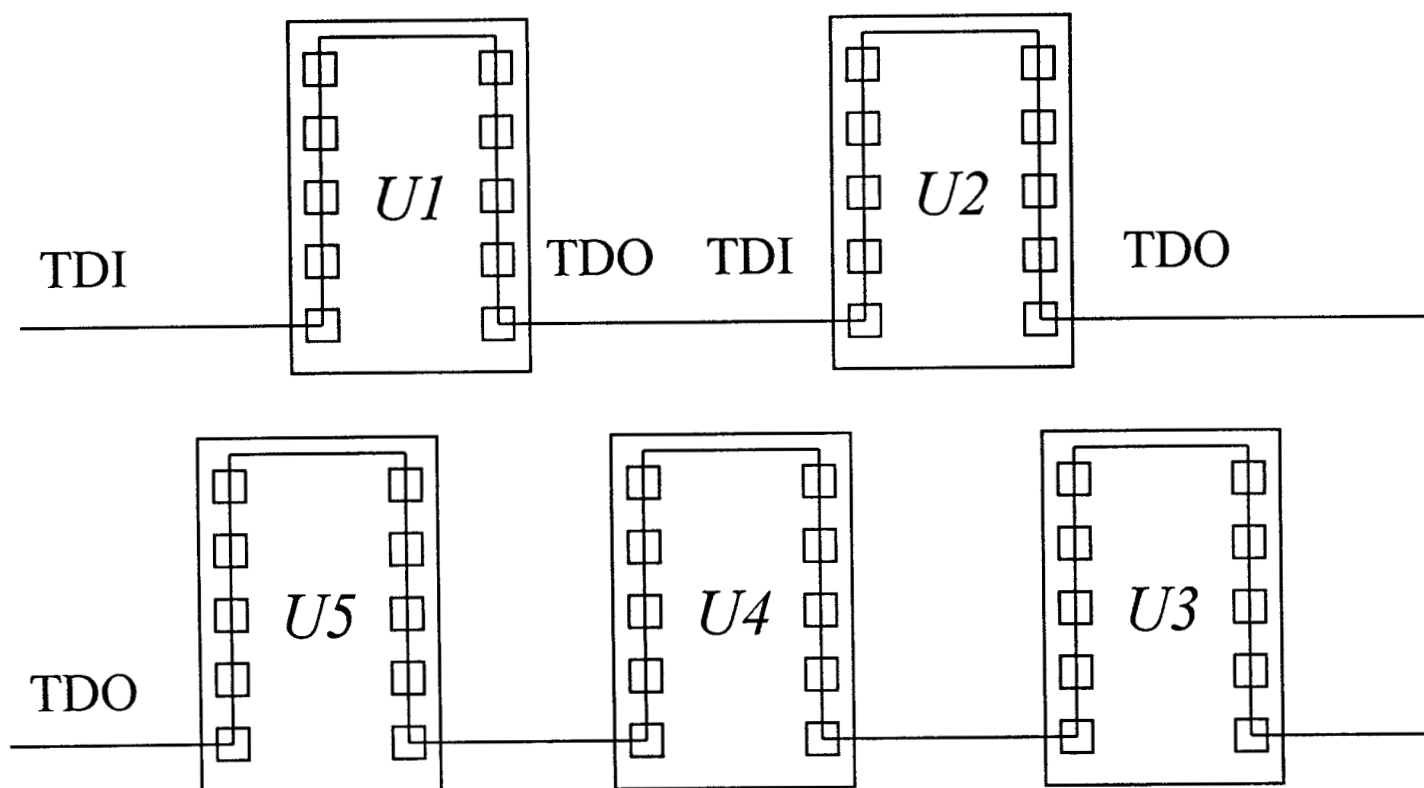
- *simple for solder joints or connectors*
- *non-powered devices*
- *don't know exactly what interconnect has failed*

Boundary Scan

- *IEEE Standard (JTAG)*
 - *Standardized*
 - *Commercially available*
- *powered devices*
- *digital test*
- *determine failure at interconnect level*
 - *short*
 - *open*



Boundary Scan Chip

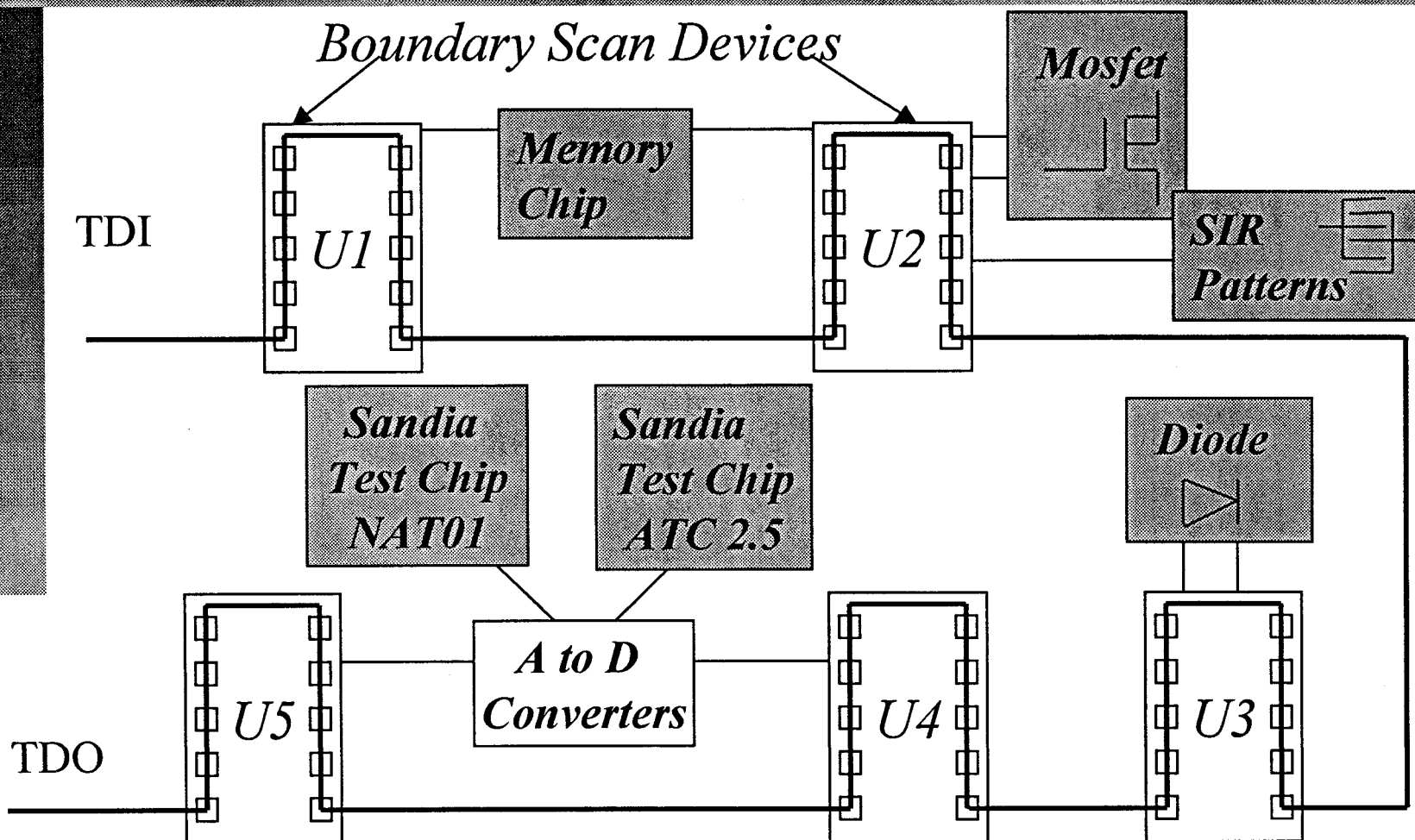


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Board Design



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Devices on Board

■ *Packaged Parts*

- *Boundary Scan Chips*
- *Resistors*
- *A to D Converters*

■ *Bare Die*

- *A Memory Chip*
- *Several Schottky Diodes*
- *MOSFETs (Both N and P Channel)*
- *Sandia Test Chips*
 - *ATC 2.5*
 - *NAT01*
- *SIR Patterns*

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Boundary Scan Test

- *Diodes - Series connected with resistor*
- *Mosfets - N and P channel configured as inverters*
- *SIR Patterns - Voltage divider will show non-zero value if current flows*
- *ATC2.5 / NAT01 - A to D Converters will sense change in voltage divider*



Test of Static Memory (SRAM) by Boundary Scan

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- *Boundary Scan used to write to SRAM*
 - *Boundary Scan Chip 1 feeds addresses*
 - *Boundary Scan Chip 1 feeds data inputs*
- *Boundary Scan used to read SRAM*
 - *Chip 1 feeds addresses*
 - *Chip 2 reads Data outputs*
- *Data shifted out - verified*

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The Boundary Scan Test System

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Asset

- *Hardware Card*
- *Interface Pod*
- *Windows Software*

ASSET Tool Box

File Design Scan Path Interconnect Memory Logic ISP Custom Utilities Windows Help

Macros

Apply To: Dcabd Hierarchy...

Source Format

☒ Macro Source

☐ Macro Executable

Processing Stages

☒ Compile

☒ Apply

Macro Filename: C:\ASSET23\DcaAsset\DCAbd\Macros\Scanpth3. Browse...

Destination File: C:\ASSET23\DcaAsset\DCAbd\Macros\Scanpth3.

Arguments:

Process Save & Close Cancel

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Scan Path ATPG: Test results for entity dcabd3. This test detects:

- Stuck-at-0 on the TDI/TDO data path.
- Inoperative TCK.
- Inoperative TMS.
- Incorrect scan path length.

Pattern Is Constant 1

Step 1. Expect the value normally captured by the BYPASS/IDCODE registers.
No failures detected.

Step 2. Expect the pattern shifted through the BYPASS/IDCODE registers.
No failures detected.

Pattern Is Constant 0

Step 1. Expect the value normally captured by the BYPASS/IDCODE registers.
No failures detected.

Step 2. Expect the pattern shifted through the BYPASS/IDCODE registers.
No failures detected.

Pattern Is Constant 0110

Step 1. Expect the value normally captured by the BYPASS/IDCODE registers.
No failures detected.

Step 2. Expect the pattern shifted through the BYPASS/IDCODE registers.
No failures detected.

INFO MAX064: C:\ASSET23\DcaAsset\DCABrd\Macros\Scanpth3.mac(247) Program ran successfully.

- *Uses
Macros to
program
test*
- *Compares
test data
out to data
expected*

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LabVIEW

- Logs time, date, and other relevant information when there is a failure
- Continuous testing

Reset Panel LOG 0 Enabled Re-Enable ALL Channels TC Selections to CHART 0 32

Date	Time	Failed Ch.	Temp.	Thermopl.	Cycles	State

Panel Log to Spreadsheet File

Append A:
Overwrite C:

Total Failures on Display
0

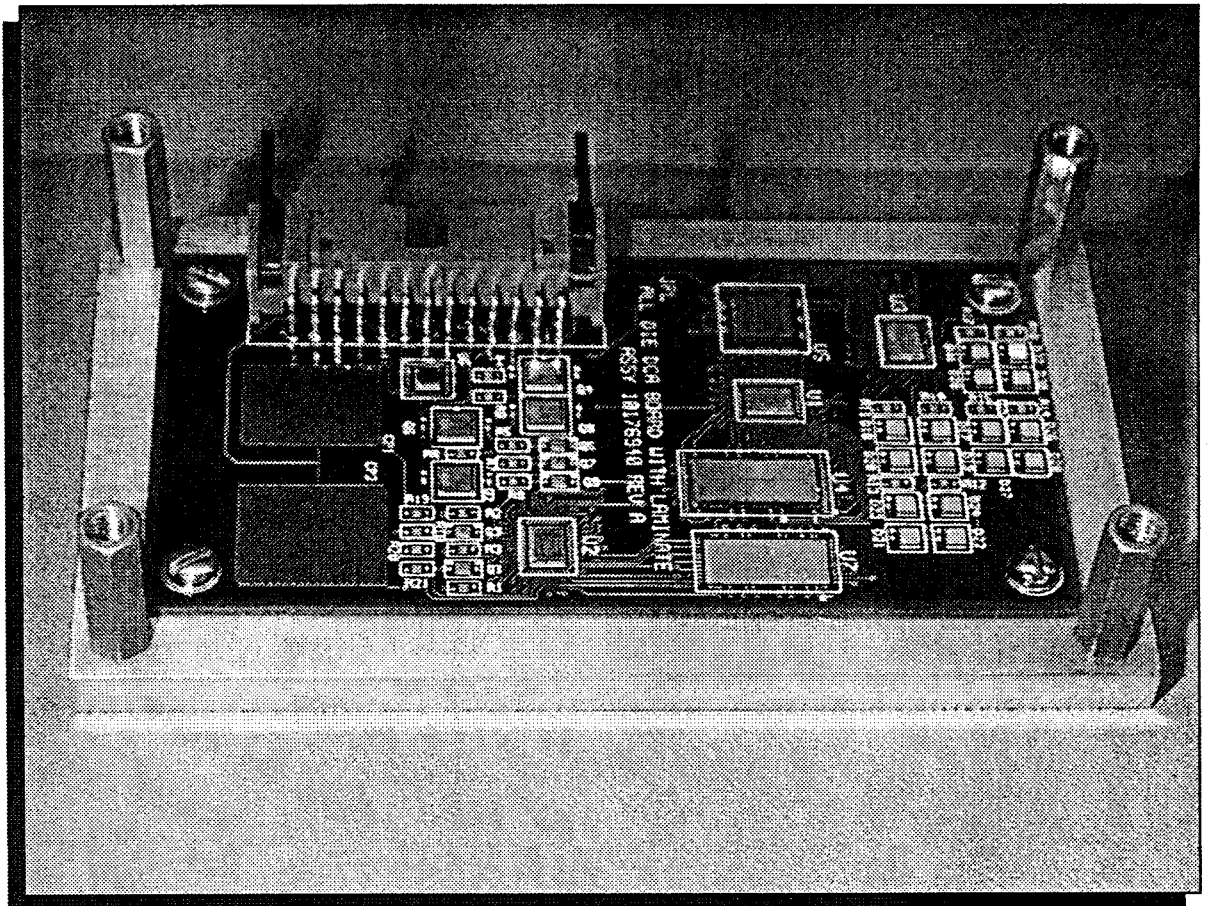
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Successfully able to test

- *diodes*
- *mosfets*
- *SRAM*



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Future Tasks

- *LabVIEW up and running*
- *Continuous testing in thermal and HAST chambers*
- *Testing all different types of new Packaging technologies*

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Summary

- *Boundary Scan use for DCA*
 - *test at interconnect level*
 - *automated testing that logs failures*
- *Boundary Scan as a valuable resource to testing new technologies*